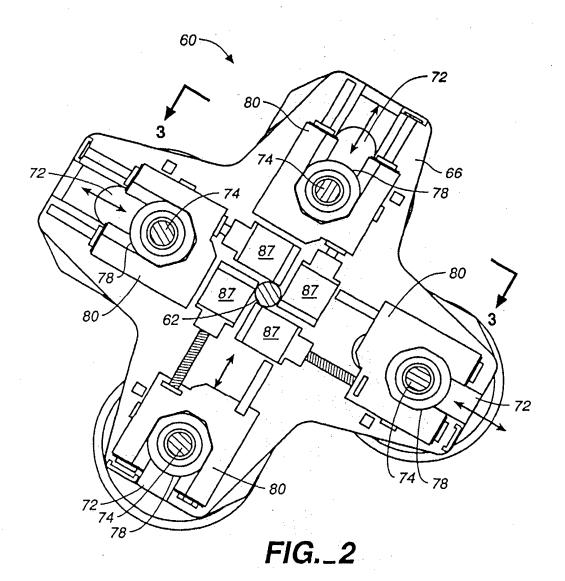
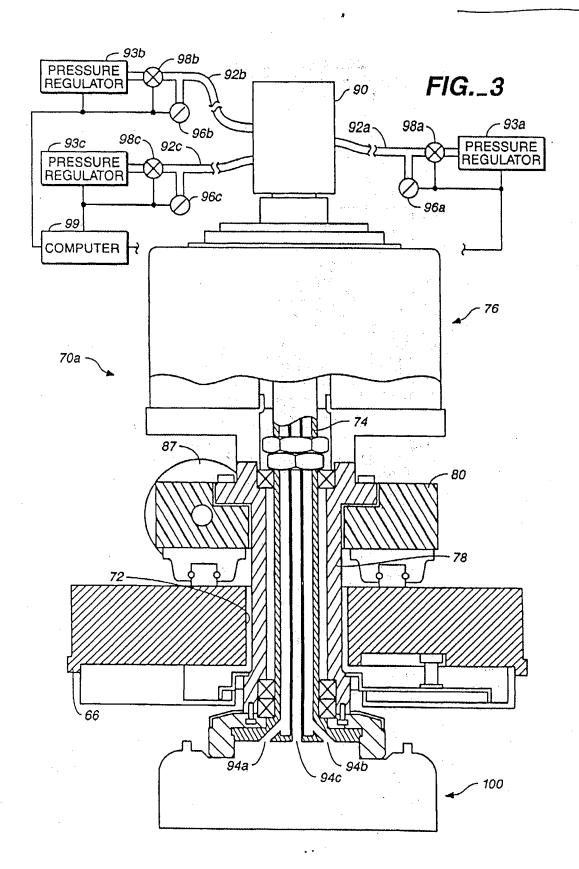


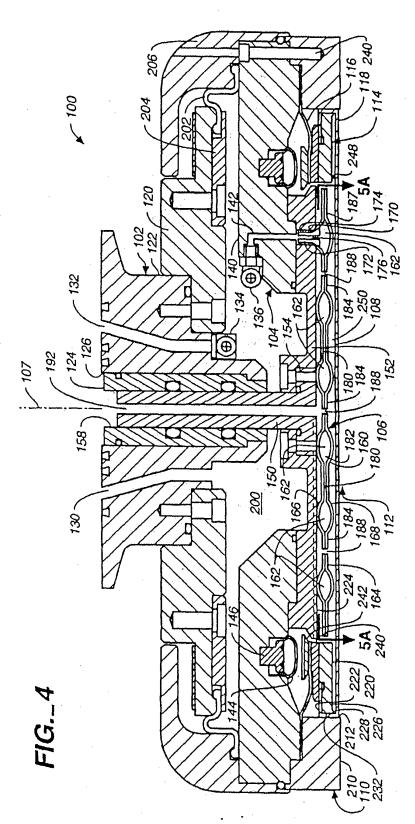
1. . Çi .



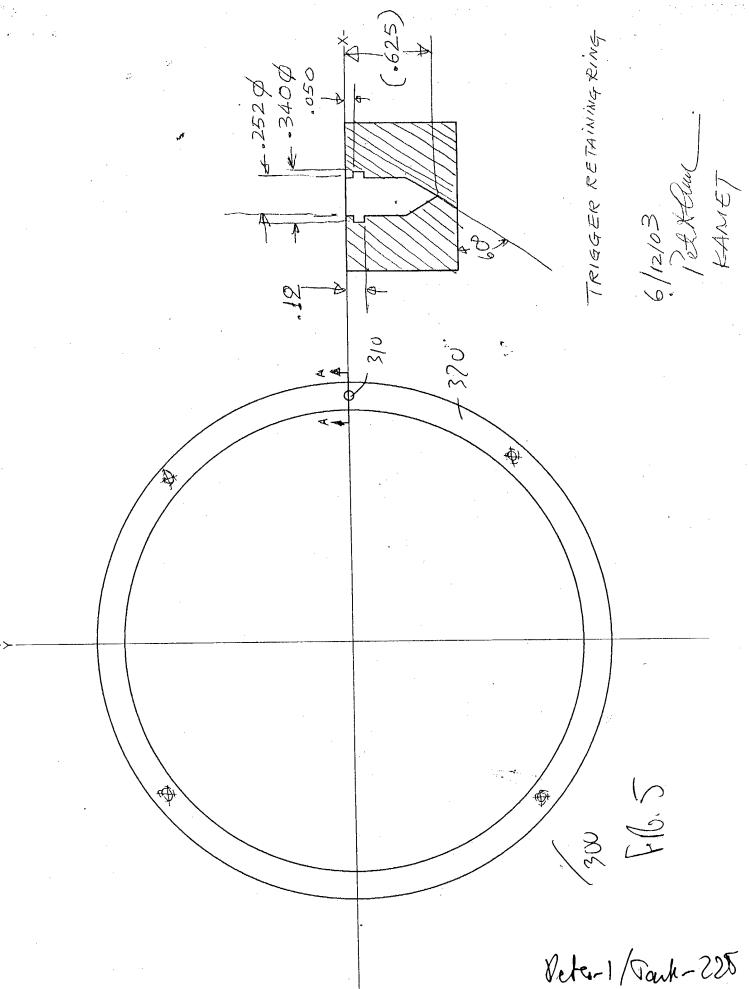
Peter -1/ Pak - 225



Petu-1/ Tank 220



Petent Frank-225



6 A

/400 F-16-6

Peter-1 Nouth -200

SHAPI OF HOCO

71 2/1/2 5/1/2 05 40

71 3/1/2 520

70 3/1/2 3/1/2 520

FOS 7A - 7 E

Position of O-Ring
600
70 \$ 580 to 580
75 \$ 570

Petr-1/5 cut 2005

BRGGER REFAINING RING C 200-3820

KAMET

-0.252Ø

0.12

652

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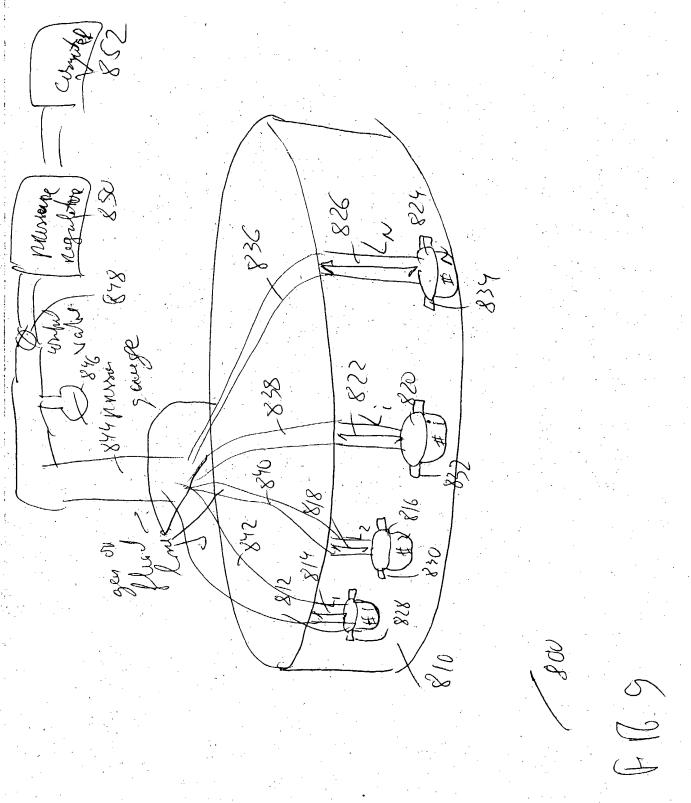
HOR CAN BE

400000 ERICONO.

Nety-1/ Tach 225

0 650

	706
()	B) substantially continuously measuring and maintaining the predetermined air
p	pressure of the selected gas in the trigger cavity.
	708
(	C) performing a chemical mechanical polishing operation on a wafer by using
tl	he CMP apparatus having the retaining ring with the single trigger cavity under
c	control of a computer loaded with a chemical mechanical polishing computer
p	orogram.
	710
-	if the air pressure in the single trigger cavity changes beyond a
	predetermined threshold level? 722
	Jej - 7720 712
(	D) using the chemical mechanical polishing computer program to stop the
ŗ	process of performing the chemical mechanical polishing operation on the wafer.
	714
(	(E) replacing the retaining ring.
_	
(	(F) repeating the steps (A-E).



Neta-1/ Tent-225

